

Wednesday, September 20

Opening Session

Session Chair: T. Endoh, Tohoku Univ.
K. Shiraishi, Nagoya Univ.

9:00 Welcome Address

H. Ohno, Tohoku Univ.

9:05 PL-1-01

The Semiconductor Industry: Changed and Unchanged
T. Higashi, Tokyo Electron Ltd.

9:50 PL-2-01

What is Next in Computing? -A Semiconductor
Perspective
P. Ranade, Intel Corp.

10:35 PL-2-02

Research on Nitride Semiconductors from the Dawn,
through the Present, to the Future
T. Matsuoka, Tohoku Univ.

11:20 SSDM Award/SSDM Papar Award Ceremony

11:40-13:30 Lunch

Luncheon Seminar

12:00-13:00

ADVANTEST CORPORATION (Hagi Conference Room)
KEYSIGHT TECHNOLOGIES (Tachibana Conference Room)

Joint Session (Area 7&12)

A-1: Magneto-Optical Devices

13:30-15:15 Meeting Room 1

Session Chair: H. Shimizu (Tokyo Univ. of Agri. & Tech.)
H. Isshiki (Univ. of Electro-Communications)

13:30 A-1-01 (Invited)

Electric, Magnetic, and Optical Control of Multiferroics
°M. Matsubara¹, ¹Tohoku Univ. (Japan)

14:00 A-1-02 (Invited)

Magneto-optical Spatial Light Modulator for 3D Holographic Display

°K. Aoshima¹, H. Kinjo¹, D. Kato¹, N. Funabashi¹, S. Aso¹, K. Machida¹, K. Kuga¹, T. Mishina¹, T. Ishibashi², H. Kikuchi¹, ¹NHK Japan Broadcasting Corp. (Japan), ²Nagaoka Univ. of Tech. (Japan)

14:30 A-1-03

Ultra-compact Circular Polarized Metal/GaN Double-Spiral Cavity Lasers

°C. A. Lin¹, S. W. Liao¹, Y. H. Hsiao¹, C. L. Yu¹, H. C. Kuo¹, M. H. Shih², ¹National Chiao Tung Univ. (Taiwan), ²RCAS, Academia Sinica (Taiwan)

14:45 A-1-04 (Invited)

Functional Oxides for Photonics

°J. Fompeyrine¹, F. Eltes¹, S. Abel¹, ¹IBM Research - Zurich (Switzerland)

15:15-15:40

Coffee Break

12: Spintronics Materials and Devices

A-2: Spinorbitronics

15:40-17:25 Meeting Room 1

Session Chair: J. Nitta (Tohoku Univ.)

T. Kondo (Toshiba Corp.)

15:40 A-2-01 (Invited)

Magnetic Skyrmions in Confined Geometries

H. Du^{1,2}, C. Jin¹, X. Wang³, R. Che³, °M. Tian^{1,2}, ¹Chinese Academy of Sci. (China), ²Anhui Univ. (China), ³Fudan Univ. (China)

16:10 A-2-02

Determination of Dzyaloshinskii-Moriya Interaction Energy by Extended Droplet Model

°S. Kim¹, P. -H. Jang², D. -H. Kim¹, M. Ishibashi¹, T. Taniguchi¹, T. Moriyama¹, K. -J. Kim^{3,1}, K. -J. Lee², T. Ono¹, ¹Kyoto Univ. (Japan), ²Korea Univ. (Korea), ³KAIST (Korea)

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16:25 A-2-03

Spin Orbit Torques in Heavy-Metal/Ferromagnet/Normal-Metal Trilayers

°Y. Du^{1,2}, Y.-C. Lau^{1,3}, J. Nitta², M. Hayashi^{1,3}, ¹Nat'l. Inst. for Mater. Sci. (Japan), ²Tohoku Univ. (Japan), ³Univ. of Tokyo (Japan)

16:40 A-2-04

Device Size Dependence of Spin-orbit Torque Induced Magnetization Switching in W/CoFeB/MgO

°C. Zhang¹, S. Fukami¹, S. DuttaGupta¹, H. Sato¹, H. Ohno¹, ¹Tohoku Univ. (Japan)

16:55 A-2-05

Detection of heating effect due to magneto-static surface spin wave in CoFeB film

°K. Yamanoi¹, T. Kimura¹, ¹Kyushu Univ. (Japan)

17:10 A-2-06

Current Density Dependence of Asymmetric Magnetoresistance in Pt/Py Bilayers Under Various Magnetic Field Strength

°T. Li¹, S. Kim¹, S. -J. Lee², S. -W. Lee², T. Koyama³, D. Chiba³, T. Moriyama¹, K. -J. Lee², K. -J. Kim^{1,4}, T. Ono^{1,5}, ¹Kyoto Univ. (Japan), ²Korea Univ. (Korea), ³Univ. of Tokyo (Japan), ⁴KAIST (Korea), ⁵Osaka Univ. (Japan)

10: Organic Materials Science, Device Physics, Applications and Printed Technologies

B-1: Organic Devices

13:30-15:15 Meeting Room 2

Session Chair: H. Okada (Univ. of Toyama)

T. Matsushima (Kyushu Univ.)

13:30 B-1-01 (Invited)

Significant Lifetime Enhancement of Organic Light Emitting Diodes by Removing Residual Water during Device Fabrication

°H. Murata¹, L. C. Duy¹, S. Oyama¹, H. Sakai¹, ¹JAIST (Japan)

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14:00 B-1-02

Introducing optical resonators into polymer light-emitting electrochemical cells

°*T. Zhang*¹, *T. Sakanoue*¹, *T. Takenobu*¹, ¹*Nagoya Univ. (Japan)*

14:15 B-1-03

Single-Crystal Perovskite CH₃NH₃PbBr₃ Prepared by Cast-capping Method for Light-Emitting Diodes

°*V. -C. Nguyen*¹, *H. Katsuki*¹, *F. Sasaki*², *H. Yanagi*¹, ¹*NAIST (Japan)*, ²*AIST (Japan)*

14:30 B-1-04 (Late News)

Compression of Organic Thin-films by Cold Isostatic Pressing for Enhanced Device Properties

°*Y. Esaki*¹, *T. Matsushima*^{1,2,3}, *C. Adachi*^{1,2,3}, ¹*Kyushu Univ. (Japan)*, ²*JST ERATO (Japan)*, ³*WPI-I2CNER (Japan)*

14:45 B-1-05

Photo-responsible polarization switching in TiOPc/P (VDF-TrFE) stacking films

°*Y. Koshiba*¹, *H. Horii*¹, *M. Morimoto*^{1,2}, *M. Misaki*^{1,3}, *T. Fukushima*¹, *K. Ishida*¹, ¹*Kobe Univ. (Japan)*, ²*Univ. of Toyama (Japan)*, ³*Kindai Univ. Tech. Col. (Japan)*

15:00 B-1-06

Shape changes of azobenzene particles induced by linearly polarized laser light

°*Y. Ohdaira*¹, *Y. Ikeda*¹, *H. Oka*¹, *K. Shinbo*¹, ¹*Niigata Univ. (Japan)*

15:15-15:40

Coffee Break

B-2: Organic Transistors

15:40-17:25 Meeting Room 2

Session Chair: *A. Fujii (Osaka Univ.)*

M. Yoshida (AIST)

15:40 B-2-01 (Invited)

Flexible Printed Organic TFT Devices and Potential Applications

°*S. Tokito*¹, ¹*Yamagata Univ. (Japan)*

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16:10 B-2-02

Temperature Dependence of Transport Properties in dinaphtho[2,3-b:2',3'-d] thiophene Thin-Film Transistors with MoO₃/Au Electrodes

S. Shaari^{1,2}, S. Naka¹, °H. Okada¹, ¹Univ. of Toyama (Japan), ²Univ. Malaysia Perlis (Malaysia)

16:25 B-2-03

Studies on correlation of surface and electrical properties in pentacene and thienoacene-based organic thin film transistors

S. Sharri^{1,2}, S. Naka¹, °H. Okada¹, ¹Univ. of Toyama (Japan), ²Univ. Malaysia Perlis (Malaysia)

16:40 B-2-04

Influence of Surface Treatment of SiO₂ Gate Insulator for Pentacene-based OFETs with Nitrogen-doped LaB₆ Bottom-Contact Electrode Formation Process

°Y. Maeda¹, M. Hiroki¹, S. Ohmi¹, ¹Tokyo Tech (Japan)

16:55 B-2-05

Crystal Structure Analyses of Organic Semiconductor Thin Films with Variable-Temperature Two-Dimensional Grazing Incidence X-ray Diffraction

°R. Abe¹, H. Kojima¹, M. Kikuchi², T. Watanabe³, T. Koganezawa³, N. Yoshimoto², I. Hirosawa³, M. Nakamura¹, ¹NAIST (Japan), ²Iwate Univ. (Japan), ³Japan Synchrotron Radiation Research Institute (Japan)

17:10 B-2-06

Temperature Dependence of Carrier Mobility on Non-Peripherally Octahexyl-Substituted Copper Phthalocyanine

°Ken Watanabe¹, Koichi Watanabe¹, N. Tohnai¹, A. Fujii¹, M. Ozaki¹, ¹Osaka Univ. (Japan)

15: Photovoltaic Materials and Devices

C-1: Si-based Solar Cells and Modules

13:30-15:15 Meeting Room 3

Session Chair: K. Ohdaira (JAIST)

Y. Kurokawa (Nagoya Univ.)

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13:30 C-1-01 (Invited)

Crystal Growth of CZ-Si and Relationship between Carrier Lifetime and Defects

^oK. Kakimoto¹, Y. Miyamura¹, H. Harada¹, L. Qin¹, S. Nakano¹, ¹Kyushu Univ. (Japan)

14:00 C-1-02

Carrier Transport across ITO/MoO_x/SiO_x/Si Interfaces

^oT. Kamioka¹, Y. Hayashi¹, Y. Isogai¹, K. Nakamura², Y. Ohshita¹, ¹Toyota Technol. Inst. (Japan), ²Meiji Univ. (Japan)

14:15 C-1-03

Effect of starting point formation on the crystallization of amorphous silicon films by flash lamp annealing

^oD. Sato¹, K. Ohdaira¹, ¹JAIST (Japan)

14:30 C-1-04

Characteristics of Heavily Phosphorus-doped Gradient Si-rich Oxide Multilayer Thin Film Structure by Spin-on Method

^oP. -R. Huang¹, S. -C. Lin¹, P. -T. Lee¹, ¹National Chiao Tung Univ. (Taiwan)

14:45 C-1-05

Guiding Principle for Crystalline Si Photovoltaic Modules with High Tolerance against Acetic Acid

Y. Hara¹, ^oA. Masuda¹, ¹AIST (Japan)

15:00 C-1-06 (Late News)

Characterization of Amorphous Silicon Passivation Layer Deposited by Facing Target Sputtering Using Temperature-Dependent Minority Carrier Lifetime Measurement

^oY. Shiratori¹, K. Nakada¹, S. Miyajima¹, ¹Tokyo Tech (Japan)

15:15-15:40

Coffee Break

C-2: Compound Semiconductor Solar Cells

15:40-16:40 Meeting Room 3

Session Chair: T. Negami (Panasonic Corp.)

H. Araki (National Inst. of Tech. Nagaoka College)

15:40 C-2-01 (Invited)

Improvement in Performance of CIGS Solar Cells by Surface Modification

°A. Yamada¹, ¹Tokyo Tech (Japan)

16:10 C-2-02

Analysis for Future Generation Solar Cells and Materials

°M. Yamaguchi¹, L. Zhu², H. Akiyama², Y. Kanemitsu³, H. Tampo⁴, H. Shibata⁴, K. -H. Lee¹, K. Araki¹, N. Kojima¹,
¹Toyota Tech. Inst. (Japan), ²Univ. of Tokyo (Japan),
³Kyoto Univ. (Japan), ⁴AIST (Japan)

16:25 C-2-03

Microstructural Characteristics of BaSi₂ Epitaxial Films Fabricated by Thermal Evaporation

°K. O. Hara¹, C. Yamamoto¹, J. Yamanaka¹, K. Arimoto¹, K. Nakagawa¹, N. Usami², ¹Univ. of Yamanashi (Japan),
²Nagoya Univ. (Japan)

04: Advanced Memory Technology

D-1: ReRAM Technology

13:30-15:00 Hagi Conference Room

Session Chair: Z. Wei (Panasonic Corp.)

F. M. Lee (Macronix International Co., Ltd.)

13:30 D-1-01 (Invited)

Physical modeling of carbon nanotube based nanoelectromechanical memory cell SET and RESET operations

°M. Stopa¹, T. Rueckes¹, ¹Nantero, Inc. (USA)

14:00 D-1-02

Differential Contact RRAM Pair for Advanced CMOS Logic NVM applications

°W. -T. Hsieh¹, C. -J. Lin¹, Y. -C. King¹, Y. -D. Chih², J. Chang², ¹National Tsing Hua Univ., Hsinchu (Taiwan),
²Taiwan Semiconductor Manufacturing Company (Taiwan)

14:20 D-1-03

Twin-bit Via RRAM in 16nm FinFET Logic Technologies

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°Y. -H. Shih¹, M. -Y. Hsu¹, Y. -C. King¹, C. -J. Lin¹,
¹National Tsing Hua Univ. (Taiwan), ²Taiwan
Semiconductor Manufacturing Company (Taiwan)

14:40 D-1-04

OxRAM integration above FDSOI transistor drain:
Integration approach and process impact on electrical
characteristics

°M. Barlas¹, L. Grenouillet¹, E. Vianello¹, V. Delaye¹, T.
Dewolf¹, G. Audoit¹, N. Rambal¹, S. Bernasconi¹, C. Vizioz¹,
N. Posseme¹, S. Barnola¹, B. Bouix¹, O. Pollet¹, C.
Comboroure², N. Allouti¹, P. Rodriguez¹, V. Beugin¹, V.
Loup¹, C. Tallaron², S. Chevalliez², R. Coquand¹, C.
Jahan¹, S. Reboh¹, A. Toffoli¹, S. Barraud¹, L. Brevard¹, Y.
Morand¹, M. Vinet¹, O. Faynot¹, L. Perniola¹, ¹CEA-LETI
(France), ²STMicroelectronics (France)

15:00-15:40

Coffee Break

D-2: Flash Memory

15:40-17:30 Hagi Conference Room

Session Chair: K. Yamamoto (Toshiba Memory Corp.)
Y. Jono (Micron Memory Japan Inc.)

15:40 D-2-01 (Invited)

FinFET Split-Gate MONOS for Embedded Flash in
16/14nm-node and Beyond

°S. Tsuda¹, Y. Kawashima¹, K. Sonoda¹, A. Yoshitomi¹, T.
Mihara¹, S. Narumi¹, M. Inoue¹, S. Muranaka¹, T.
Maruyama¹, T. Yamashita¹, Y. Yamaguchi¹, D. Hisamoto²,
¹Renesas Electronics Corp. (Japan), ²Hitachi, Ltd. (Japan)

16:10 D-2-02

P-channel Differential Multiple-Time Programmable
Memory Cells by Laterally Coupled Floating Metal Gate
FinFETs

°T. -M. Wang¹, W. -Y. Chien¹, C. -L. Hsu¹, Y. -D. Chih², C. J.
Lin¹, Y. -C. King¹, ¹National Tsing Hua Univ. (Taiwan),
²Taiwan Semiconductor Manufacturing Company (Taiwan)

16:30 D-2-03

In-situ formation of Hf-based MONOS structure for

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nonvolatile memory application

°S. Kudoh¹, M. Tsukazaki¹, S. Ishimatsu¹, S. Ohmi¹, ¹Tokyo Tech (Japan)

16:50 D-2-04

23% Higher Performance 2D MLC/3D TLC NAND Flash Hybrid Solid-State Drive

°Y. Sakaki¹, T. Yamada¹, C. Matsui¹, Y. Yamaga¹, K. Takeuchi¹, ¹Chuo Univ. (Japan)

17:10 D-2-05

Read Disturb Improvement for 1znm TLC NAND Flash

°H. -N. Yoo¹, H. Shim¹, J. -W. Kim¹, K. -H. Noh¹, H. Chang¹, ¹SK Hynix Inc. (Korea)

03: CMOS Devices / Device Physics

E-1: Reliability

13:30-15:15 Tachibana Conference Room

Session Chair: N. Sugii (Hitachi, Ltd.)

N. Mori (Osaka Univ.)

13:30 E-1-01 (Invited)

Reliability Characterizations for high-performance, low-power 10nm-FinFET technology

°K. Choi¹, M. Jin¹, Jinju Kim¹, Jungin Kim¹, H. Sagong¹, Y. Kim¹, H. Shim¹, K. Kim¹, G. Kim¹, S. Lee¹, T. Uemura¹, J. Park¹, S. Shin¹, S. Pae¹, ¹Samsung Electronics Co., Ltd. (Korea)

14:00 E-1-02

Comprehensive Analysis of Low-frequency Noise Variability Components in Bulk and FDSOI (SOTB) MOSFETs

°K. Maekawa¹, H. Makiyama¹, Y. Yamamoto¹, T. Hasegawa¹, S. Okanishi¹, K. Sonoda¹, H. Shinkawata¹, T. Yamashita¹, S. Kamohara¹, Y. Yamaguchi¹, ¹Renesas Electronics Corp. (Japan)

14:20 E-1-03

Plasma Induced Damage Depending on Antenna Layers in

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Ring Oscillators

°R. Kishida¹, J. Furuta¹, K. Kobayashi¹, ¹Kyoto Inst. of Tech. (Japan)

14:40 E-1-04

Revisited Study for Fluorine Implantation Impact on NBTI for Automotive I/O Device

°T. Yoshida¹, K. Maekawa¹, S. Tsuda¹, T. Shimizu¹, M. Ogasawara¹, H. Aono¹, ¹Renesas Electronics Corp. (Japan)

15:00 E-1-05 (Late News)

Improved Performance and Sufficient Reliability

In_{0.53}Ga_{0.47}As FinFET Using NH₃ Plasma Treatment

°K. S. Yang¹, Q. -H. Luc¹, C. C. Chang¹, J. W. Lin¹, C. -C. F. Chiang¹, H. B. Do¹, M. T. H. Ha¹, S. H. Huynh¹, Y. D. Jin¹, T. A. Nguyen¹, Y. -C. Lin¹, E. Y. Chang¹, ¹National Chiao Tung Univ. (Taiwan)

15:15-15:40

Coffee Break

Joint Session (Area 1&3)

E-2: Advanced Transistor Technology

15:40-17:30 Tachibana Conference Room

Session Chair: H. Morioka (Socionext Inc.)

O. Weber (CEA-Leti)

15:40 E-2-01 (Invited)

Stacked-Wires FETs for Advanced CMOS Scaling

°S. Barraud¹, V. Lapras¹, M. P. Samson², B. Previtali¹, J. M. Hartmann¹, N. Rambal¹, C. Vizioz¹, V. Loup¹, C. Comboroure², F. Triozon¹, N. Bernier¹, D. Cooper¹, M. Vinet¹, ¹CEA-Leti (France), ²STMicroelectronics (France)

16:10 E-2-02

Effect of SiGe Layer Thickness in Starting Substrate on Electrical Properties of Ultrathin Body Ge-on-Insulator pMOSFET Fabricated by Ge Condensation

°K. -W. Jo¹, W. -K. Kim¹, M. Takenaka¹, S. Takagi¹, ¹Univ. of Tokyo (Japan)

16:30 E-2-03

Single and Double Diffusion Breaks in 14nm FinFET and Beyond

°K. Miyaguchi¹, F. Bufler¹, T. Chiarella¹, P. Matagne¹, N. Horiguchi¹, A. D. Keersgieter¹, G. Eneman¹, A. Spessot¹, B. Parvais^{1,2}, D. Verkest¹, A. Mocuta¹, ¹IMEC (Belgium),
²Vrije Universiteit Brussel (Belgium)

16:50 E-2-04

Insights and Opportunities for Junctionless Gate-All-Around Lateral and Vertical Nanowire FETs

°A. Veloso¹, P. Matagne¹, E. Simoen¹, A. Chasin¹, B. Kaczer¹, D. Yakimets¹, D. Mocuta¹, N. Collaert¹, ¹IMEC (Belgium)

17:10 E-2-05

High Performance Top-Gate Zinc Oxide Thin Film Transistor (ZnO TFT) by Combination of Post Oxidation and Annealing

°K. Kato¹, H. Matsui¹, H. Tabata¹, M. Takenaka¹, S. Takagi¹, ¹Univ. of Tokyo (Japan)

Joint Session (Area 5&11)

F-1: Advanced Materials & Measurement Circuits for Bio and Medical Applications

13:30-15:05 Meeting Room 4

Session Chair: C. H. Liu (National Tsing Hua Univ.)
T. Yoshida (Hiroshima Univ.)

13:30 F-1-01 (Invited)

The Next Generation Biochip: The Development of Polysilicon Nanowire Effect Transistor Based Biosensor Array

°Y. -S. Yang¹, P. -C. Su¹, Y. -S. Wu¹, C. -L. Hsieh¹, S. -K. Shen¹, ¹National Chiao Tung Univ. (Taiwan)

14:00 F-1-02

A potable bioactive monitoring device for observing water transport in plants with a non-invasive technique

°M. Haruta¹, M. Kubo¹, T. Noda¹, K. Sasagawa¹, T.

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Tokuda¹, J. Ohta¹, ¹NAIST (Japan)

14:15 F-1-03

An Integrated Photo-Plethysmography Recording Circuit for Trans-Nail Pulse-Wave Monitoring System

°Z. Qian¹, Y. Takezawa¹, K. Shimokawa¹, H. Kino¹, T. Fukushima¹, K. Kiyoyama², T. Tanaka¹, ¹Tohoku Univ. (Japan), ²Nagasaki Inst. of Applied Sci. (Japan)

14:30 F-1-04

CMOS-based Opical Energy Harvesting Circuit for Implantable and IoT Devices

°N. Wuthibenjaphonchai¹, M. Haruta¹, T. Noda¹, K. Sasagawa¹, T. Tokuda¹, M. Sawan², J. Ohta¹, ¹NAIST (Japan), ²Polytechnique Montreal (Canada)

14:45 F-1-05

A Compact Sweat Monitoring System with CMOS Capacitive Humidity Sensor for Wearable Health-Care Application

°Y. Mitani¹, K. Miyaji¹, S. Kaneko¹, T. Uekura¹, H. Momose², K. Johguchi¹, ¹Shinshu Univ. (Japan), ²Nishizawa Electric Meters Manufacturing Co., Ltd. (Japan)

15:05-15:40

Coffee Break

11: Sensors and Materials for Biology, Chemistry and Medicine

F-2: Bio and Micro Systems

15:40-17:10 Meeting Room 4

Session Chair: T. Sakata (Univ. of Tokyo)

H. M. Chen (NCTU)

15:40 F-2-01 (Invited)

Biodevice Technologies for Cancer Diagnosis Using Exosome-based Biomarkers

°T. Ichiki^{1,2}, ¹Univ. of Tokyo (Japan), ²Kawasaki Inst. of Industry Promotion (Japan)

16:10 F-2-02

Respiratory Sensor Continuously Attached on the Abdomen

*M. Terasawa¹, M. Karita¹, S. Kumagai¹, °M. Sasaki¹,
¹Toyota Tech. Inst. (Japan)*

16:25 F-2-03

Wireless operation of EWOD by the on-chip CMOS silicon photovoltaic cell array

°Y. Okamoto¹, Y. Mita¹, ¹Univ. of Tokyo (Japan)

16:40 F-2-04

Development of Vertically-Stacked Multi-Shank Si Neural Probe Array with Sharpened Tip for Cubic Spatial Recording

°T. Harashima¹, T. Morikawa¹, H. Kino¹, T. Fukushima¹, N. Katayama¹, T. Tanaka¹, ¹Tohoku Univ. (Japan)

16:55 F-2-05

Parallelized High Throughput Emulsification and Emulsion PCR for Clinical Use of BEAMing Technology

*°K. Cai¹, Y. Koya¹, K. Yasuko¹, N. Katsumi¹, T. Ayato¹,
¹Sysmex Corp. (Japan)*

07: Photonic Devices and Related Technologies

G-2: GaN Photonic Devices

15:40-16:55 Meeting Room 5

Session Chair: S. Kuboya (Tohoku Univ.)

T. Tawara (NTT Basic Res. Labs.)

15:40 G-2-01 (Invited)

Current Status and Future of III-Nitride Ultraviolet and THz Emitters

°H. Hirayama^{1,2}, M. Jo¹, W. Terashima^{1,2}, N. Maeda^{1,2}, T. -T. Lin², K. Wang², ¹RIKEN (Japan), ²RIKEN Center for Advanced Photonics (Japan)

16:10 G-2-02

Ultraviolet light emitting diodes grown on Si-implanted GaN template

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°P. -H. Liao¹, H. -Y. Cheng¹, M. -L. Lee², W. -C. Lai¹, J. -K. Sheu¹, ¹National Cheng Kung Univ. (Taiwan), ²Southern Taiwan Univ. of Sci. and Tech. (Taiwan)

16:25 G-2-03

Reduction of Impurity Incorporation into MOVPE-grown GaN films on ScAlMgO₄ Substrate

°T. Iwabuchi¹, S. Kuboya¹, C. Hagiwara¹, T. Tanikawa¹, T. Hanada¹, T. Fukuda², T. Matsuoka¹, ¹Tohoku Univ. (Japan), ²Fukuda Crystal Lab. (Japan)

16:40 G-2-04

Enhanced Hole Generation in Mg-doped AlN/AlGaN Superlattices with High Average Al Content

°K. Ebata¹, J. Nishinaka¹, Y. Taniyasu¹, K. Kumakura¹, ¹NTT Basic Res. Labs. (Japan)

Joint Session (Area 2&13)

H-1: Nanocarbon Interconnects and Applications

13:30-15:15 Meeting Room 6

Session Chair: T. Minari (NIMS)

T. Arie (Osaka Prefecture Univ.)

13:30 H-1-01 (Invited)

Nanocarbon application including interconnects and thermal interface materials

°D. Kondo¹, S. Sato¹, T. Iwai¹, N. Yokoyama¹, ¹Fujitsu Labs. Ltd. (Japan)

14:00 H-1-02

Moisture Barrier Properties of Single-Layer Graphene Deposited on Cu Films for Cu Metallization

°P. Gomasang¹, T. Abe¹, K. Kawahara², Y. Wasai³, N. Nabatova-Gabain³, N. T. Cuong⁴, H. Ago², S. Okada⁵, K. Ueno^{1,6}, ¹Shibaura Inst. of Tech. (Japan), ²Kyushu Univ. (Japan), ³Horiba Ltd. (Japan), ⁴NIMS (Japan), ⁵Univ. of Tsukuba (Japan), ⁶SIT Res. Center for Green Innov. (Japan)

14:15 H-1-03

Developing Lightweight High Electrical Performance Carbon Nanotube-Cu Wire Composites as Alternatives to Cu

^oR. Sundaram¹, T. Yamada¹, K. Hata¹, A. Sekiguchi¹, ¹AIST (Japan)

14:30 H-1-04

Pd-dot-size dependence of hydrogen sensors based on graphene FET for breath analysis

^oY. Sakamoto¹, K. Uemura¹, T. Ikuta¹, K. Maehashi¹, ¹Tokyo Univ. of Agri. & Tech. (Japan)

14:45 H-1-05

Intrinsic response of protein adsorption to graphene film on SiC substrate

^oY. Taniguchi¹, M. Tsubasa¹, Y. Ohno¹, M. Nagase¹, Y. Arakawa¹, Y. Imada¹, K. Minagawa¹, M. Yasuzawa¹, ¹Tokushima Univ. (Japan)

15:00 H-1-06

Growth of Suspended Graphene Nanoribbons and its Optoelectronic Application

^oH. Suzuki¹, T. Kaneko¹, T. Kato¹, ¹Tohoku Univ. (Japan)

15:15-15:40

Coffee Break

02: Interconnect Technologies, MEMS, and Reliability

H-2: MEMS & Sensors

15:40-17:50 Meeting Room 6

Session Chair: H. Kanaya (Kyushu Univ.)

S. Itabashi (NTT Advanced Tech. Corp.)

15:40 H-2-01 (Invited)

Pharmaceutical Contaminants and pH Sensing using MWCNTs based Electrodes

A. U. Alam¹, N. -X. Hu², ^oM. R. Howlader¹, M. J. Deen¹, ¹McMaster Univ. (Canada), ²Xerox Research Center of Canada (Canada)

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16:10 H-2-02

Silicon Photonic Biosensors with MEMS Flow Control

°Y. Amemiya¹, A. K. Sana¹, Y. Nakashima¹, J. Maeda¹, S. Yokoyama¹, ¹Hiroshima Univ. (Japan)

16:30 H-2-03

Tilt Characteristics of a MEMS Accelerometer fabricated by Multi-layer Metal Technology

°I. Tsuji¹, M. Takayasu¹, H. Ito¹, D. Yamane¹, S. Dosho¹, T. Konishi^{1,2}, N. Ishihara¹, K. Machida¹, K. Masu¹, ¹Tokyo Tech (Japan), ²NTT Adv. Tech. Corp. (Japan)

16:50 H-2-04

The Fully Wireless Pressure Sensor Based on Endoscopic Image

°Y. Maeda^{1,2}, H. Mori¹, T. Nakagawa¹, H. Takao¹, ¹Kagawa Univ. (Japan), ²National Institute of Technology, Kagawa Collage (Japan)

17:10 H-2-05

Development of an Adhesive Plaster Size Current Sensor for Power Monitoring

°T. Yamashita¹, T. Itoh², R. Maeda¹, ¹AIST (Japan), ²Univ. of Tokyo (Japan)

17:30 H-2-06

Evaluation of Electrical Conductivity of CFRP by Surface Potential Distribution

°K. Kikunaga¹, N. Terasaki¹, ¹AIST (Japan)

08: Advanced Material Synthesis and Crystal Growth Technology
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J-1: Oxide based Materials

13:30-15:15 Meeting Room 7

Session Chair: T. Nagata (NIMS)

T. Yamaguchi (Kogakuin Univ.)

13:30 J-1-01 (Invited)

Utilizing Reflection High Energy Electron Diffraction to Map Growth Windows in Hybrid Molecular Beam Epitaxy

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°R. Engel-Herbert¹, M. Brahlek¹, J. M Lapano¹, J. Roth¹,
¹Pennsylvania State Univ. (USA)

14:00 J-1-02

Growth and Magnetic Properties of Ruddlesden-Popper Series $\text{Sr}_{n+1}\text{V}_n\text{O}_{3n+1}$ Epitaxial Thin Films

°S. Fukuda¹, D. Oka¹, T. Fukumura¹, ¹Tohoku Univ. (Japan)

14:15 J-1-03

Comparative study of Al and V co-doped ZnO thin films on quartz, polyethylene terephthalate, and polycarbonate substrates

°C. Tateyama¹, H. Chiba^{1,2}, T. Kawashima¹, K. Washio¹,
¹Tohoku Univ. (Japan), ²Japan Society for the Promotion of Sci. Res. Fellowships for Young Scientists (Japan)

14:30 J-1-04

Composition Control of ZnMgO Thin-films by Mist Chemical Vapor Deposition

°P. Rutthongjan¹, ¹Kochi Univ. of Technology (Japan)

14:45 J-1-05

Mist CVD process including successive deposition of Al_2O_3 , Fe catalyst layers and carbon nanotubes for high density forest

°T. Kinoshita¹, M. Karita¹, T. Nakano¹, Y. Inoue¹, T. Miwa²,
H. Nagaoka², ¹Shizuoka Univ. (Japan), ²JNC Petrochemical (Japan)

15:00 J-1-06

Investigation of the effective net charge of strontium silicate layers on silicon substrates at changing annealing condition

°S. Taniwaki¹, H. Yoshida¹, K. Arafune¹, A. Ogura², S. Satoh¹, Y. Hotta¹, ¹Univ. of Hyogo (Japan), ²Meiji Univ. (Japan)

15:15-15:40

Coffee Break

13: Applications of Nanotubes, Nanowires, and Graphene and related 2D materials

J-2: 2D Materials and Devices

15:40-17:25 Meeting Room 7

Session Chair: K. Nagashio (Univ. of Tokyo)

T. Takenobu (Nagoya Univ.)

15:40 J-2-01 (Invited)

Two-Dimensional Materials: from Contact to Device Applications

P. -W. Chiu^{1,2}, P. -H. Ho¹, °C. -H. Yeh¹, W. -H. Wang², C. -H. Ho³, C. -W. Chen⁴, ¹National Tsing Hua Univ. (Taiwan), ²Academia Sinica (Taiwan), ³National Taiwan Univ. of Sci. and Tech. (Taiwan), ⁴National Taiwan Univ. (Taiwan)

16:10 J-2-02

Infrared Black Phosphorus Phototransistor with Electrostatically Tunable Responsivity

°L. Huang¹, W. C. Tan¹, L. Wang¹, C. Lee¹, K. -W. Ang¹, ¹National Univ. of Singapore (Singapore)

16:25 J-2-03

Modulation of Thermoelectric Performance by Using Electrolyte Gating Method

°K. Kanahashi¹, J. Pu², L. -J. Li³, M. Ishihara⁴, M. Hasegawa⁴, Y. -Y. Noh⁵, H. Ohta⁶, T. Takenobu², ¹Waseda Univ. (Japan), ²Nagoya Univ. (Japan), ³KAUST (Saudi Arabia), ⁴AIST (Japan), ⁵Dongguk Univ. (Korea), ⁶Hokkaido Univ. (Japan)

16:40 J-2-04

Detuning dependence of higher-order harmonic generation in monolayer transition metal dichalcogenides

°T. Tamaya^{1,2}, S. Konabe³, S. Kawabata^{1,2}, ¹AIST (Japan), ²CREST, Japan Sci. and Tech. Agency (Japan), ³Tokyo Univ. of Sci. (Japan)

16:55 J-2-05

Tailoring the Rashba Spin-Orbit Coupling in Colloidal Lead Sulfide Nanosheets

°M. M. Ramin Moayed¹, T. Bielewicz¹, M. S. Zoellner¹, C.

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Herrmann¹, C. Klinke¹, ¹Univ. of Hamburg (Germany)

17:10 J-2-06

Tunable spin splitting and spin relaxation in polar WSTe monolayer

^oM. A. U. Absor¹, F. Ishii², H. Kotaka³, M. Saito², ¹Gadjah Mada Univ. (Indonesia), ²Kanazawa Univ. (Japan), ³Osaka Univ. (Japan)

01: Advanced LSI Processing & Materials Science
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K-1: Interface Engineering

13:30-15:20 Meeting Room 8

Session Chair: H. Nohira (Tokyo City Univ.)

S. Yoshida (Sony Semiconductor Solutions Corp.)

13:30 K-1-01 (Invited)

Interface Dipole Layers between Two Dielectrics:
Considerations on Physical Origins and Opportunities to
Control Their Formation

^oK. Kita¹, H. Kamata¹, J. Fei¹, ¹Univ. of Tokyo (Japan)

14:00 K-1-02

Direct Observation of Electrical Dipole and Atomic
Density at High-k Dielectrics/SiO₂ Interface

^oN. Fujimura¹, A. Ohta¹, M. Ikeda¹, K. Makihara¹, S. Miyazaki¹, ¹Nagoya Univ. (Japan)

14:20 K-1-03

Consideration on the interfacial dipole layer formation at
non-SiO₂ oxide interfaces in the examples of MgO/Al₂O₃
and HfO₂/Al₂O₃

^oJ. Fei¹, K. Kita¹, ¹Univ. of Tokyo (Japan)

14:40 K-1-04

Characterization of near-interface border-traps in GeO₂/Ge
gate stacks grown by low and high temperature thermal
oxidation using deep-level transient spectroscopy

^oW.-C. Wen¹, T. Sakaguchi¹, K. Yamamoto¹, D. Wang¹, H. Nakashima¹, ¹Kyushu Univ. (Japan)

15:00 K-1-05

Generalized Picture of Work Function of a Metal with Schottky Interface

°*T. Nishimura¹, T. Yajima¹, A. Toriumi¹, ¹Univ. of Tokyo (Japan)*

15:20-15:40

Coffee Break

05: Advanced Circuits and Systems

K-2: Advanced Power Converters and Packaging Technologies

15:40-17:15 Meeting Room 8

Session Chair: H. Lin (National Chung Hsing Univ.)
I. Akita (Toyohashi Tech)

15:40 K-2-01

A 190mV Start-up Voltage Doubler Charge Pump with CMOS Gate Boosting Technique in 0.18 μ m Standard CMOS Process for Energy Harvesting

°*M. Yoshida¹, K. Miyaji¹, ¹Shinshu Univ. (Japan)*

16:00 K-2-02

A Wide Load Range Switched Capacitor DC-DC Converter with Adaptive Bias Comparator for Ultra-Low-Power Power Management Integrated Circuit

°*H. Asano¹, T. Hirose¹, Y. Kojima¹, N. Kuroki¹, M. Numa¹, ¹Kobe Univ. (Japan)*

16:20 K-2-03

Comparisons of Wire Bonding and Flip-Chip Bonding Assembly in High Frequency Hysteretic DC-DC Buck Converters

°*Y. Karasawa¹, Y. Gotou¹, S. Hara¹, T. Fukuoka¹, K. Miyaji¹, ¹Shinshu Univ. (Japan)*

16:40 K-2-04

A Compact Size, Wide-Range Efficiency, and Self-biasing CMOS-IPD Rectenna Using 2.5D Wafer-level Packing for a Biomedical Wireless Power Transfer System

°*K. -C. Lin¹, P. -C. Wu¹, T. -Y. Lin¹, Y. -C. Liu¹, W. -T. Hung¹, H. -H. Tsai¹, Y. -Z. Juang¹, ¹Chip Implementation*

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Center (Taiwan)

17:00 K-2-05 (Late News)

Wide-range bioelectrical impedance analysis circuit with GIDL-controlled ultrasmall current and ultralow frequency square wave generator

°Y. Takezawa¹, K. Shimokawa¹, Z. Qian¹, H. Kino¹, T. Fukushima¹, K. Kiyoyama², T. Tanaka¹, ¹Tohoku Univ. (Japan), ²Nagasaki Inst. of Applied Sci. (Japan)

Joint Session (Area 4&9)

M-1: Quantum vs Classical

13:30-15:15 Meeting Room 2

Session Chair: T. Sakamoto (NEC Corp.)

T. Tanamoto (Toshiba Corp.)

13:30 M-1-01 (Invited)

CMOS Ising Computing for Combinatorial Optimization Problems

°M. Yamaoka¹, ¹Hitachi, Ltd. (Japan)

14:00 M-1-02 (Invited)

Scalability of diamond-based quantum information devices

°K. Nemoto^{1,2}, M. Hanks^{2,1}, M. Trupke^{3,4}, J. Schmiedmayer⁴, W. J. Munro^{5,1}, ¹National Inst. of Informatics (Japan), ²Sokendai, The Graduate Univ. for Advanced Studies (Japan), ³Univ. of Vienna (Austria), ⁴Vienna Center for Quantum Sci. and Tech. (Austria), ⁵NTT Basic Res. Labs. (Japan)

14:30 M-1-03

Quantum Dipole in a Silicon Transistor: Quantum Simulation for Strongly Correlated System

°S. Saito¹, Z. Li¹, H. Yoshimoto², I. Tomita^{1,3}, Y. Tsuchiya¹, Y. Sasago⁴, H. Arimoto^{1,4}, F. Liu¹, M. K. Husain¹, D. Hisamoto⁴, H. N. Rutt¹, S. Kurihara², ¹Univ. of Southampton (UK), ²Waseda Univ. (Japan), ³Gifu College (Japan), ⁴Hitachi, Ltd. (Japan)

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14:45 M-1-04 (Late News)

Sarcosine as prostate cancer biomarker detection through H₂O₂ sensing by using nickel-oxide on Si nanowires
°A. Roy¹, S. Jana¹, J. T. Qiu¹, S. Maikap¹, ¹Chang Gung Univ. (Taiwan)

15:00 M-1-05 (Late News)

High pH sensitivity and low concentration detection of urea/H₂O₂ by using IrO_x/HfO_x membrane in electrolyte-insulator-semiconductor structure
°S. Jana¹, A. Roy¹, J. T. Qiu¹, S. Maikap¹, ¹Ghang Gung Univ. (Taiwan)

15:15-15:40	Coffee Break
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M-2: Non von Neumann Computing I

15:40-17:25 Meeting Room 2

Session Chair: T. Tanamoto (Toshiba Corp.)
Y. Nishi (Toshiba Corp.)

15:40 M-2-01 (Invited)

Memory devices in Neuromorphic Computing Systems
°C. Reita¹, ¹CEA-Leti (France)

16:10 M-2-02 (Invited)

Emulating Synaptic Plasticity in Neuromorphic Systems with Resistive Memories
°S. L. Barbera¹, E. Vianello¹, T. Werner¹, B. D. Salvo¹, L. Perniola¹, ¹CEA-Leti (France)

16:40 M-2-03 (Invited)

Low Power Deep Neural Network Hardware Based on Memristive Crossbar Circuits
°I. Kataeva¹, S. Ohtsuka¹, ¹DENSO Corp. (Japan)

17:10 M-2-04

Predictive Analysis of Randomness in 3D RRAM-based Physically Unclonable Security Primitive
°J. Kim¹, H. Nili², G. C. Adam^{2,3}, D. Strukov², O. Kavehei¹,
¹RMIT Univ. (Australia), ²Univ. of California Santa Barbara (USA), ³National Inst. for R&D in Microtechnologies (Romania)

06: Compound Semiconductor Electron Devices & Related Technologies

N-1: High-Speed and High-Frequency Devices

13:30-15:15 Meeting Room 3

Session Chair: A. Wakejima (Nagoya Inst. of Tech.)

K. Maezawa (Univ. of Toyama)

13:30 N-1-01 (Invited)

THz Circuitry Designs Based on InP and CMOS Devices

°Y. Kawano¹, H. Matsumura¹, Y. Yagishita¹, Y. Nakasha¹, T. Takahashi¹, N. Hara¹, ¹Fujitsu Ltd. (Japan)

14:00 N-1-02

A Wide-Range Variable-Frequency Resonant Tunneling Diode Oscillator Based on a Novel MEMS Phase Shifter

°T. Yamashita¹, D. Nakano¹, M. Mori¹, K. Maezawa¹, ¹Univ. of Toyama (Japan)

14:15 N-1-03

Etching Control in Side-Recess Formation of High Electron Mobility Transistor for High-Responsivity Terahertz Detector

°S. Suzuki¹, S. Shibuya¹, Y. Isobe¹, ¹Tokyo Tech (Japan)

14:30 N-1-04

Enhanced-Mode InAs QWFETs with the Source Connected Field Plate Technique for Low Power Logic Applications

°J. N. Yao¹, Y. C. Lin¹, H. T. Hsu¹, T. J. Huang¹, M. S. Lin², Y. C. Wang¹, Z. Y. Huang¹, S. M. Sze¹, E. Y. Chang¹, ¹National Chiao Tung Univ. (Taiwan), ²National Tsing Hua Univ. (Taiwan)

14:45 N-1-05

Study of enhance mode π -gate InAs HEMT for logic application

°Y. -C. Wang¹, J. -N. Yao¹, Y. -C. Lin¹, H. -T. Hsu¹, T. -J. Huang¹, C. -Y. Huang¹, E. Y. Chang¹, ¹National Chiao Tung Univ. (Taiwan)

15:00 N-1-06

First Demonstration of GaSb p-Channel Schottky

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MOSFET with Pt Source/Drain

°M. L. Tsai¹, Y. P. Chang¹, C. H. Chien¹, ¹National Chiao Tung Univ. (Taiwan)

15:15-15:40

Coffee Break

Joint Session (Area 6&8&14)

N-2: Advanced Growth of Widegap Semiconductors

15:40-17:25 Meeting Room 3

Session Chair: N. Shigekawa (Osaka City Univ.)

T. Nagata (NIMS)

15:40 N-2-01 (Invited)

Recent Progress in MOCVD Technology: III-Nitrides and 2D Nanomaterials

°M. Heuken^{1,2}, ¹AIXTRON SE (Germany), ²RWTH Aachen Univ. (Germany)

16:10 N-2-02

Thermodynamic Analysis of the Surface Reactions in GaN MOVPE

°K. Sekiguchi¹, H. Shirakawa¹, K. Chokawa¹, M. Araidai¹, Y. Kangawa^{1,2}, K. Kakimoto², K. Shiraishi¹, ¹Nagoya Univ. (Japan), ²Kyushu Univ. (Japan)

16:25 N-2-03

Improved mobility in InAlN/AlGaN two-dimensional electron gas heterostructures with an atomically-smooth heterointerface

°D. Hosomi¹, Y. Miyachi¹, T. Egawa¹, M. Miyoshi¹, ¹Nagoya Inst. of Tech. (Japan)

16:40 N-2-04

Relationship between Current Density and Stacking Fault Expansion Origin in Forward Degradation of 4H-SiC PiN Diodes

°S. Hayashi^{1,2}, T. Yamashita^{1,3}, J. Senzaki¹, M. Miyazato^{1,4}, M. Ryo^{1,4}, M. Miyajima^{1,4}, Y. Yonezawa¹, T. Kato¹, K. Kojima¹, H. Okumura¹, ¹AIST (Japan), ²Toray Research Center Inc. (Japan), ³SHOWA DENKO K.K. (Japan), ⁴Fuji Electric Co. Ltd. (Japan)

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16:55 N-2-05

Fabrication of MSM-Type Photodetector Using Sn-Doped α -Ga₂O₃ Films Grown by Mist Chemical Vapor Deposition
°K. Rikitake¹, T. Kobayashi¹, T. Yamaguchi¹, T. Onuma¹, T. Honda¹, ¹Kogakuin Univ. (Japan)

17:10 N-2-06 (Late News)

AlN metal-semiconductor field-effect transistors using Si-ion implantation

°H. Okumura^{1,2}, S. Suihkonen³, J. Lemettinen³, A. Uedono¹, T. Palacios², ¹Univ. of Tsukuba (Japan), ²MIT (USA), ³Aalto Univ. (Finland)

14: Power Devices and Materials

O-1: SiC Power Devices and Related Technologies

13:30-15:15 Meeting Room 4

Session Chair: H. Fujiwara (Toyota Motor Corp.)
D. Hisamoto (Hitachi, Ltd.)

13:30 O-1-01 (Invited)

Accurate Evaluation of Fast Threshold Voltage Shift for SiC MOS Devices Under Various Gate Bias Stress Conditions

°M. Sometani¹, M. Okamoto¹, T. Hatakeyama¹, Y. Iwahashi¹, M. Hayashi^{1,2}, D. Okamoto³, H. Yano³, S. Harada¹, Y. Yonezawa¹, H. Okumura¹, ¹AIST (Japan), ²DENSO Corp. (Japan), ³Univ. of Tsukuba (Japan)

14:00 O-1-02

First Principles Study of the effect of Hydrogen Annealing effects on SiC MOSFETs

°K. Chokawa¹, K. Shiraishi¹, ¹Nagoya Univ. (Japan)

14:15 O-1-03

Kinetics of Enhanced Oxide Growth on 4H-SiC in O₂ and H₂O Coexisting Ambient

°K. Ishinoda¹, K. Kita¹, ¹Univ. of Tokyo (Japan)

14:30 O-1-04

Oxidation-induced Lattice Distortion at 4H-SiC (0001)

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Surface Characterized by Surface Sensitive In-plane X-ray
Diffractometry

°A. D. Hatmanto¹, K. Kita¹, ¹Univ. of Tokyo (Japan)

14:45 O-1-05

Hole Trapping in SiC-MOS Devices Evaluated by Fast-CV
Method

°M. Hayashi^{1,2}, M. Sometani¹, T. Hatakeyama¹, H. Yano³, S.
Harada¹, ¹AIST (Japan), ²DENSO Corp. (Japan), ³Univ.
of Tsukuba (Japan)

15:00 O-1-06 (Late News)

Effect of Surface Roughness of Trench Sidewalls on
Channel Mobility in 4H-SiC Trench MOSFETs

°K. Kutsuki¹, Y. Murakami¹, Y. Watanabe², T. Onishi¹, K.
Yamamoto³, H. Fujiwara¹, T. Ito¹, ¹Toyota Motor Corp.
(Japan), ²Toyota Central R&D Labs. Inc. (Japan),
³DENSO Corp. (Japan)